

Messen
Prüfen
Kontrollieren
Sortieren
Positionieren
Vollständigkeitskontrolle
Vorhandenseinskontrolle
Oberflächeninspektion
Teileprüfung
Werkzeugvoreinstellung
3D Sehen
3D Erkennung
Robot Vision
Markierungskontrolle
Koplanarität
BGA-Prüfung
Konturprüfung
Fehler- und Verschmutzungserkennung
OCR / OCV
Zeichenerkennung
Code Lesen
Faden- und Stoffprüfung
Papier- und Folienprüfung
Metallprüfung
Displayprüfung LCD, LED, OLED
Mustervergleich
Blasenkontrolle
Robotersteuerung
Bohrer Vermessung
Thermografie
Plastik-Inspektion
2D
und vieles mehr...

Product data:

EyeScan LTZ 3D



Description:

The EyeScan LTZ 3D is a very compact and fast laser triangulation sensor. It is specially suitable for profile scans, for example glue and sealing bead inspection as well as bin-picking

It is supported by the EyeVision 3D software and all the software functions and commands are available for the user.

The LTZ 3D has a Dual-Core ARM processor and an FPGA for fast preprocessing of the data.

More information on our Website: www.evt-web.com.

Please do not hesitate to contact us if you have any questions:

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Technical Data EyeScan LTZ 3D Series

| | Specification |
|----------------------|--|
| Laser | Class 2, wave length 450 nm, < 100mW average |
| Sensor | CMOS 1/2.9" sony IMX273LLR, monochrome |
| Active pixels | 1408 (H) x 1080 (V) |
| Pixel size | 3.45 (H) x 3.45 (V) μ m |



| | |
|-----------------------------|---|
| Active Sensor Size | 4.8 (H) x 3.7 (V) mm |
| High-speed Shutter | 1 μ s + steps of 1 μ s |
| Integration | Global Shutter |
| Data aquisition | Program-controlled or external high speed trigger, full-frame up to 174 frames per second, jitterfree acquisition |
| A/D conversion | 10 bit, 8 bits used after LUT application |
| Input LUT | 1024 x 8 bits |
| Image Display | Via Ethernet onto PC |
| Processor | Dual-Core ARM Cortex A9 with 866MHz and integrated FPGA |
| FPGA | Laser line processing during image acquisition in FPGA |
| RAM | 512 MB DDR-SDRAM |
| Flash EPROM | 16 GB flash memory (nonvolatile) industrial eMMC |
| Encoder Inputs | Yes, and encoder inputs can be used as additional 5-24V inputs |
| Trigger Input | Encoder Signal A can be used as trigger input |
| Ethernet Interface | 1Gbit / 100 Mbit / 10 Mbit |
| Storage Conditions | -20 .. +60 $^{\circ}$ C, Max. humidity: 90 %, non-condensing |
| Operating Conditions | 0 .. +50 $^{\circ}$ C, Max. humidity: 80 %, non-condensing |
| Power Supply | 24V DC, 300 mA without I/O usage |
| Power Consumption | 7.2 W typical without I/O usage |

| EyeScan LTZ 3D | (8/30) regular | (8/34) regular | (8/30) large | (8/34) large | (8/30) xlarge | (8/34) xlarge | (8/30) xxlarge | (8/34) xxlarge | (6/32) regular |
|-----------------------------|-------------------|-------------------|-----------------|-----------------|------------------|------------------|-------------------|-------------------|-------------------|
| Min. distance Z (mm) | 90 | 80 | 170 | 150 | 285 | 245 | 460 | 400 | 70 |
| Max. distance Z (mm) | 245 | 195 | 470 | 375 | 785 | 625 | 1285 | 1020 | 285 |
| Min. horiz. FoV X (mm) | 65 | 65 | 130 | 120 | 215 | 200 | 350 | 325 | 80 |
| Max. horiz. FoV X (mm) | 150 | 125 | 295 | 240 | 495 | 400 | 810 | 660 | 230 |
| Resolution X Min [μ m] | 60 | 50 | 110 | 100 | 170 | 160 | 280 | 260 | 70 |
| Resolution X Max [μ m] | 120 | 100 | 240 | 190 | 390 | 320 | 640 | 520 | 190 |
| Resolution Z Min [μ m] | 10 | 10 | 20 | 20 | 30 | 30 | 40 | 40 | 10 |
| Resolution Z Max [μ m] | 40 | 30 | 80 | 60 | 130 | 90 | 220 | 150 | 70 |